

SY75572L

267 MHz 1:2 3.3V HCSL/LVDS Fanout Buffer

Features

- Two Differential Pairs of LVDS or HCSL Outputs
- Two Pairs of Differential Inputs Accept LVDS or HCSL Logic Levels
- 267 MHz Maximum Frequency
- · Ultra-Low Phase Jitter:
 - 137 fs_{RMS}, 200 MHz (12 kHz 20 MHz)
 - 153 fs_{RMS}, 156.25 MHz (12 kHz 20 MHz)
 - 212 fs_{RMS}, 100 MHz (12 kHz 20 MHz)
- <2 ps Total Jitter (peak-to-peak), 200 MHz (BER = 10⁻¹²)
- 50 ps Output-to-Output Skew
- 3.3V ±5% Power Supply Operation
- –40°C to +85°C Operating Temperature
- Available in 16-pin (3 mm × 3 mm) QFN Lead-Free Package

Applications

- Blade Servers
- Desktop Servers
- Workstations
- Storage Area Networks
- · IP Routers and Switches
- Telecom and Datacom
- High Performance Computing

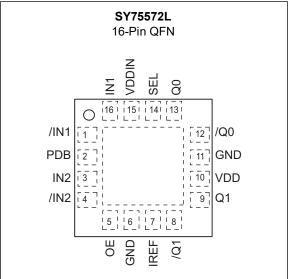
General Description

The SY75572L is a high-speed, fully differential 1:2 clock fanout buffer with a 2:1 input MUX optimized to provide two identical output copies with 137 fs phase jitter and a maximum of 50 ps output-to-output skew. Designed to be used with PCI Express applications, the SY75572L accepts and outputs HCSL or LVDS logic levels.

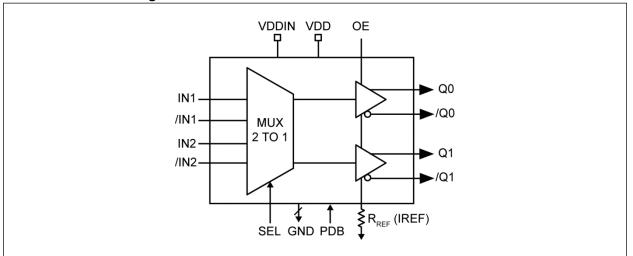
The SY75572L operates from a $3.3V \pm 5\%$ power supply and is guaranteed over the full industrial temperature range (-40°C to +85°C). It is available in a 16-pin QFN lead-free package.

The SY75572L is part of Microchip's high-speed, ultra-low jitter, PrecisionEdge™ product line. The SY75572L supports PCIe Gen1-Gen4 requirements.

Package Type



Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Supply Voltage, V _{CC,} V _{DDIN}	5.5V
Input Voltage, V _{IN}	-0.5V to VDDN +0.5V
ESD Protection (Input)	
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Operating Ratings ++

Supply Vol	Itage, V _{DD.}	V _{DDIN}	135V to 3.465V
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† Notice: Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.
 † Notice: The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.

DC ELECTRICAL CHARACTERISTICS

Electrical Characteristics: $V_{DD} = V_{DDIN} = 3.135V$ to 3.465V, $T_A = -40^{\circ}C$ to +85°C, unless otherwise stated. R_{BEE} = 475\Omega. (Note 1)

Parameters	Symbol	Min.	Тур.	Max.	Units	Conditions
Power Supply Voltage Range	V _{DD} , V _{DDIN}	3.135	3.3	3.465	V	_
Input Capacitance	C _{IN}		_	6	pF	_
Output Capacitance	C _{OUT}	_	_	5	pF	_
Pin Inductance	L _{PIN}	_		4	nH	_
Output Resistance	R _{OUT}	3			kΩ	—
Pull up Resistance	R _{PULL-UP}	_	110		kΩ	SEL, PDB, OE
Input High Voltage	V _{IH}	2		V _{DDIN} + 0.3	V	SEL, PDB, OE
Input Low Voltage	V _{IL}	-0.3		0.8	V	SEL, PDB, OE
Input High Voltage	V _{IH}	350		850	mV	HCSL, IN, /IN
Input Low Voltage	V _{IL}	-150	0	_	mV	HCSL, IN, /IN
Differential Input Voltage Range	V _{IN}	200	350	550	mV	LVDS, IN, /IN
Input Common Mode Voltage	VINPUT OFFSET	1.125	1.25	1.375	V	LVDS, IN, /IN
Output High Voltage	V _{OH}	660	750	850	mV	HCSL
Output Low Voltage	V _{OL}	-150	0	27	mV	HCSL
Crossing Point Voltage Note 2, Note 3	V _{CROSS}	250	350	550	mV	Absolute
Variation of Crossing Point Voltage Note 2, Note 3, Note 4	V _{CROSS_VARIATION}	_		140	mV	Variation over all edges
			42	60		50Ω, 2 pF
Power Supply Current For V _{DD} + V _{DDIN}	I _{DD}	_		0.4	mA	No load, PDB = Low
				20		OE = Logic Low
Input Leakage Current Note 5	Ι _{ΙL}	-5		5	μA	$0 < V_{IN} < V_{DDIN}$

Note 1: The circuit is designed to meet the DC specifications shown in the table above after thermal equilibrium has been established.

2: Test setup is $R_L = 50\Omega$ with 2 pF, $R_{REF} = 475\Omega \pm 1\%$.

- 3: Measurement taken from Q and /Q.
- 4: Measured at the crossing point where instantaneous voltages of Q and /Q are equal.
- 5: Inputs with pull-up/pull-down resistances are not included.

AC ELECTRICAL CHARACTERISTICS

Electrical Characteristics: $V_{DD} = V_{DDIN} = 3.135V$ to 3.465V, $T_A = -40^{\circ}C$ to +85°C, unless otherwise stated. (Note 1)									
Parameters	Symbol	Min.	Тур.	Max.	Units	Conditions			
M	4		_	267	N 41 1-	HCSL			
Maximum Frequency	f _{MAX}	_	—	100	MHz	LVDS			
Propagation Delay	t _{PD}		2	3	ns	Note 2			
Output-to-Output skew	t _{SKEW}	—	—	50	ps	Note 3, Note 4			
Output Rise/Fall Times 0.175V to 0.525V / 0.525V to 0.175V	t _r , t _f	150	350	700	ps	At full output swing. 50Ω , 2 pF			
Rise/Fall Time Variation	t _{r/f_VAR}	_	_	125	ps	At full output swing. 50Ω , 2 pF			
			137	—	fs _{RMS}	At 200 MHz			
Phase Jitter	t _{JITTER}		153	_	fs _{RMS}	At 156.25 MHz			
			212	_	fs _{RMS}	At 100 MHz			
Total Jitter	t _{tj_jitter}	—	2		ps	BER = 10 ⁻¹² , T _{DJ} = 0, at 200 MHz			
Output Enable Time	t _{OE_ENABLE}		2	_	μs	All outputs			
Output Disable Time	t _{OE_DISABLE}		10	_	ns	All outputs			
Duty Cycle	t _{DCY}	45	50	55	%	—			

Note 1: The circuit is designed to meet the DC specifications shown in the table above after thermal equilibrium as been established.

2: Measured from the differential input crossing point to the differential output crossing point.

3: Output-to-output skew is the difference in time between outputs, receiving data from the same input, for the same temperature, voltage, and transition.

4: This parameter is defined in accordance with JEDEC Standard 65.

TEMPERATURE SPECIFICATIONS

Parameters	Symbol	Min.	Тур.	Max.	Units	Conditions	
Temperature Ranges							
Operating Temperature Range	T _A	-40	_	+85	°C	—	
Lead Temperature	—		_	+260	°C	Soldering, 20 sec.	
Storage Temperature Range	Τ _S	-65	_	+150	°C	—	
Package Thermal Resistance (Note 1)							
	θ _{JA}		59	_	°C/W	Still-Air	
16-Pin QFN	ΨJB		38	_	°C/W	Junction-to-board	

Note 1: Package thermal resistance assumes exposed pad is soldered (or equivalent) to the device's most negative potential on the PCB. ψ_{JB} and θ_{JA} values are determined for a 4-layer board in still-air number, unless otherwise stated. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

Pin Number	Pin Name	Description
1	/IN1	HCSL/LVDS inverted input 1.
2	PDB	PDB = 0 powers down the chip and tri-states outputs. The pin is attached to an internal pull-up resistor.
3	IN2	HCSL/LVDS input 2.
4	/IN2	HCSL/LVDS inverted input 2.
5	OE	Tri-state outputs. High = enable outputs. Low = disable outputs. Internal pull-up resistor, outputs are enabled by default.
6	GND	Ground.
7	IREF	External resistor R _{REF} between pin IREF and GND controls reference current.
8	/Q1	Inverted Output 1.
9	Q1	Non-inverted Output 1.
10	VDD	3.3V power supply.
11	GND	Ground.
12	/Q0	Inverted Output 0.
13	Q0	Non-inverted Output 0.
14	SEL	SEL = 0 propagates IN2, /IN2 to outputs. SEL = 1 propagates IN1, /IN1 to outputs. Internal pull-up resistors, IN1, /IN1 is selected by default.
15	VDDIN	3.3V power supply.
16	IN1	HCSL/LVDS input 1.

TABLE 2-1: PIN FUNCTION TABLE

3.0 JITTER ANALYSIS

Jitter is defined as the deviation of a signal from its ideal position. Phase noise is the presence of signal energy at frequencies other than the carrier. Random jitter has a Gaussian distribution and is specified as an RMS unit, which is one standard deviation of the distribution. Since Gaussian distribution is unbounded in an infinite sample, no communication system can be completely error free. Instead, communication links are rated with a maximum bit error rate (BER), which is typically around 10^{-12} for high-speed communication equipment. Achieving a desired BER requires accounting for a number of standard deviations of random noise by using the appropriate value for N (see Table 3-1) in the formula in Equation 3-1.

EQUATION 3-1:

 $T_J = N \times R_J + D_J$

Where:

R_J = Random jitter

D_J = Deterministic jitter

If routing clock signals, the deterministic jitter is usually negligible and the T_J is dominated by the random jitter. Calculating T_J from R_J using Equation 3-1 gives the values in Table 3-1.

TABLE 3-1:	STANDARD DEVIATIONS OF
	RANDOM NOISE

BER	N	R _J at 200 MHz	T _J at 200 MHz
10 ⁻¹⁰	12.723	137fs _{RMS}	1.743 ps
10 ⁻¹¹	13.412	137fs _{RMS}	1.837 ps
10 ⁻¹²	14.069	137fs _{RMS}	1.927 ps
10 ⁻¹³	14.698	137fs _{RMS}	2.013 ps

4.0 PHASE NOISE PLOTS

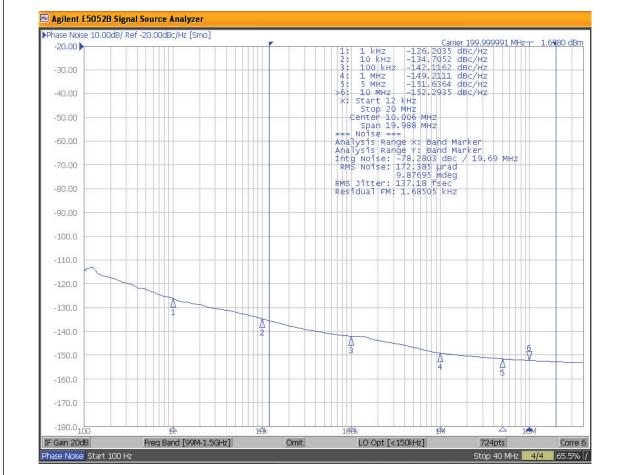


FIGURE 4-1: Phase Jitter = 137 fsRMS, 200 MHz Carrier Frequency; Integration Range: 12 kHz - 20 MHz.

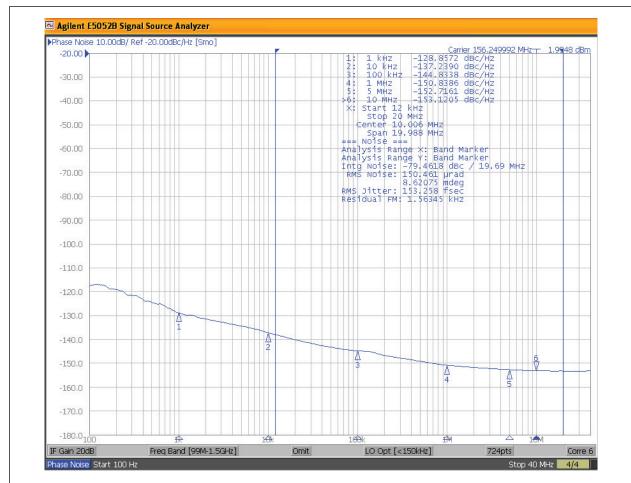


FIGURE 4-2: Phase Jitter = 153 fsRMS, 156.25 MHz Carrier Frequency; Integration Range: 12 kHz - 20 MHz.

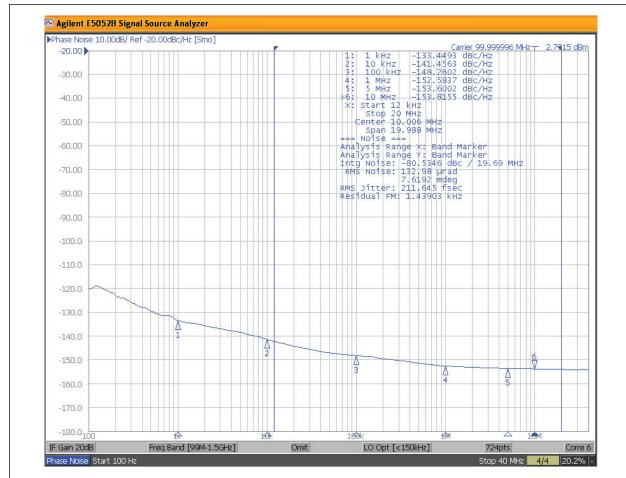
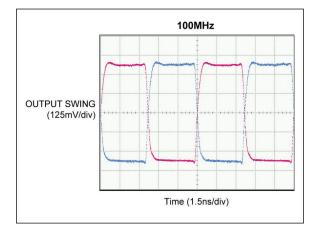
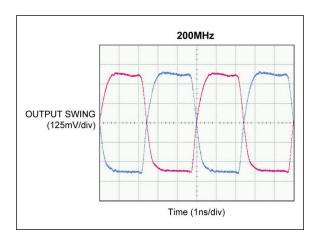
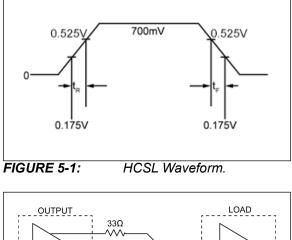


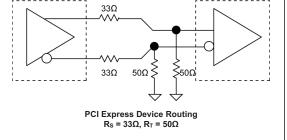
FIGURE 4-3: Phase Jitter = 212 fs_{RMS}, 100 MHz Carrier Frequency; Integration Range: 12 kHz - 20 MHz.

5.0 FUNCTIONAL CHARACTERISTICS











HCSL Interface Application.

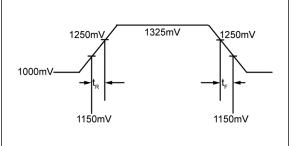
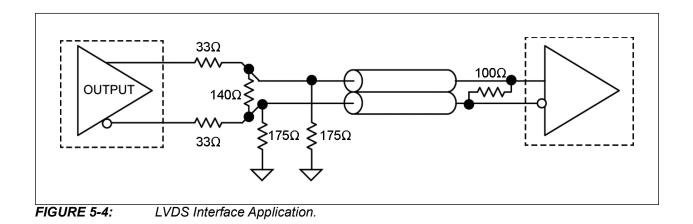
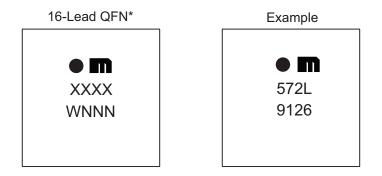


FIGURE 5-3: LVDS Waveform.

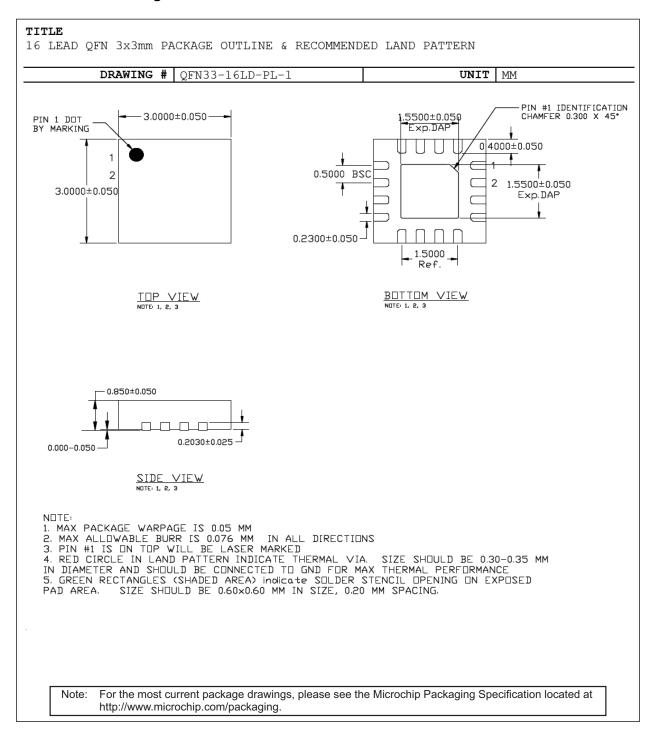


6.0 PACKAGING INFORMATION

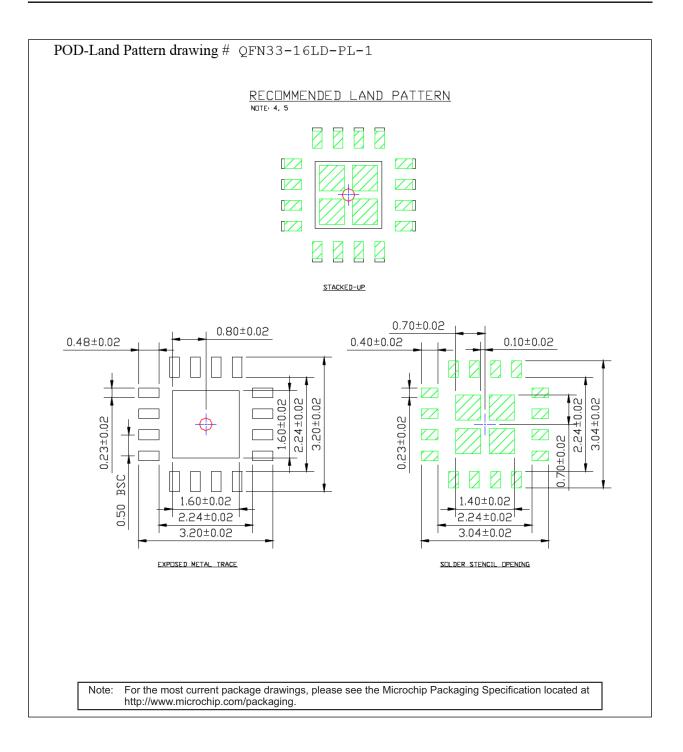
6.1 Package Marking Information



Legend:	XXX	Product	CO	de d	or	custor	ner-spe	cific	infor	mation
	Y	Year	code	de (last		digit of caler			ndar	year)
	ΥY	Year	code	(last	2	digits	of	cale	endar	year)
	WW	Week	code	(week	of	Janua	iry 1	is	week	'01')
	NNN	Alphanu	meric			tracea	ability			code
	e3	Pb-free	JEDI	EC [®] (desig	nator	for	Matte	Tin	(Sn)
	*	This package is Pb-free. The Pb-free JEDEC designat(e3) can be found on the outer packaging for this package.							3))	
	●, ▲, ▼ mark).	Pin one	index is	identified	l by a	a dot, del	ta up, o	r delta	down (t	riangle
	te: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.									
	Underbar	(_) and/or	Overba	ır (⁻) sym	bol n	nay not b	e to sca	ale.		



16-Lead QFN Package Outline and Recommended Land Pattern



APPENDIX A: REVISION HISTORY

Revision A (March 2022)

- Converted Micrel document SY75572L to Microchip data sheet template DS20006669A.
- Minor text changes throughout.

Revision B (May 2023)

• Updated HCSL Input High and Low Voltage information in the DC Electrical Characteristics table. NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

					E	amples:				
PART #. Device	X Supply Voltage Range	X Package	X Junction Temperature Range	XX Special Processing	a)	SY75572 16-Lead	, 3.3V QFN, ure Range, 100	Outpu –40°C)/Tube		5572LMG: Voltage, +85°C
Device:	SY75572:		, 2.5 GHz Differer CML Delay Line	ntial Two-Channel	b)	SY75572 16-Lead	QFN,	Outpu –40°C		2LMG-TR: Voltage, +85°C
Supply Voltage:	L =	3.3V				iemperat	ure Range, 1,0	UU/Reel		
Package:	M =	16-Lead QF	N							
Temperature Range:	G =	-40°C to +8	5°C (NiPdAu Lea	ad Free)	N	Ca	ape and Reel ide atalog part numb sed for ordering e device packad	er description purposes and	n. This i d is not j	dentifier is printed on
Special Processing:	<blank> = <t r=""> =</t></blank>					S	ales Office for pa ape and Reel op	, ackage availa		

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